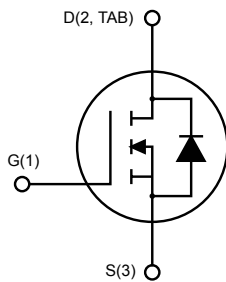
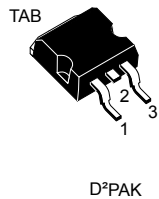


N-channel 650 V, 95 mΩ typ., 24 A MDmesh™ M5 Power MOSFET in D²PAK package



Features

| Order codes | V _{DS} at T _{jmax.} | R _{DS(on)} max. | I _D |
|-------------|---------------------------------------|--------------------------|----------------|
| STB32N65M5 | 710 V | 119 mΩ | 24 A |

- Extremely low R_{DS(on)}
- Low gate charge and input capacitance
- Excellent switching performance
- 100% avalanche tested

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET based on the MDmesh™ M5 innovative vertical process technology combined with the well-known PowerMESH™ horizontal layout. The resulting product offers extremely low on-resistance, making it particularly suitable for applications requiring high power and superior efficiency.



Product status link

[STB32N65M5](#)

Product summary

| | |
|-------------------|--------------------|
| Order code | STB32N65M5 |
| Marking | 32N65M5 |
| Package | D ² PAK |
| Packing | Tape and reel |

1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|------------|------------------|
| V_{GS} | Gate-source voltage | ± 25 | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 24 | A |
| I_D | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 15 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 96 | A |
| P_{TOT} | Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 150 | W |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 15 | V/ns |
| T_j | Operating junction temperature range | -55 to 150 | $^\circ\text{C}$ |
| T_{stg} | Storage temperature range | | |

1. Pulse width limited by safe operating area.

2. $I_{SD} \leq 24\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DS(peak)} \leq V_{(BR)DSS}$.

Table 2. Thermal data

| Symbol | Parameter | Value | Unit |
|---------------------|----------------------------------|-------|---------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case | 0.83 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb | 30 | $^\circ\text{C}/\text{W}$ |

1. When mounted on FR-4 board of 1 inch², 2oz Cu.

Table 3. Avalanche characteristics

| Symbol | Parameter | Value | Unit |
|----------|--|-------|------|
| I_{AR} | Avalanche current, repetitive or not-repetitive (pulse width limited by T_j Max) | 8 | A |
| E_{AS} | Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$) | 650 | mJ |

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|---|------|------|-----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$ | 650 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{DS} = 650\text{ V}$, $V_{GS} = 0\text{ V}$, | | | 1 | μA |
| | | $V_{DS} = 650\text{ V}$, $V_{GS} = 0\text{ V}$, $T_C = 125\text{ °C}$ ⁽¹⁾ | | | 100 | μA |
| I_{GSS} | Gate body leakage current | $V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$ | 3 | 4 | 5 | V |
| $R_{DS(on)}$ | Static drain-source on resistance | $V_{GS} = 10\text{ V}$, $I_D = 12\text{ A}$ | | 95 | 119 | m Ω |

1. Defined by design, not subject to production test.

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------------------|---------------------------------------|---|------|------|------|---------------|
| C_{iss} | Input capacitance | $V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$ | - | 3320 | - | μF |
| C_{oss} | Output capacitance | | | 75 | | |
| C_{riss} | Reverse transfer capacitance | | | 5 | | |
| $C_{o(tr)}$ ⁽¹⁾ | Equivalent capacitance time related | $V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ to }520\text{ V}$ | - | 210 | - | μF |
| $C_{o(er)}$ ⁽²⁾ | Equivalent capacitance energy related | | | 70 | | |
| R_g | Gate input resistance | $f = 1\text{ MHz}$, $I_D = 0\text{ A}$ | - | 2 | - | Ω |
| Q_g | Total gate charge | $V_{DD} = 520\text{ V}$, $I_D = 12\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 15. Test circuit for gate charge behavior) | - | 72 | - | nC |
| Q_{gs} | Gate-source charge | | | 17 | | |
| Q_{gd} | Gate-drain charge | | | 29 | | |

1. $C_{o(tr)}$ time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

2. $C_{o(er)}$ energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(off)}$ | Turn-off delay time | $V_{DD} = 400\text{ V}$, $I_D = 15\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times and Figure 19. Switching time waveform) | - | 53 | - | ns |
| t_r | Rise time | | | 12 | | |
| t_c | Cross time | | | 29 | | |
| t_f | Fall time | | | 16 | | |

Table 7. Source drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit | |
|-----------------|-------------------------------|--|------|------|------|------|----|
| I_{SD} | Source-drain current | | - | | 24 | A | |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | | | 96 | | |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 24\text{ A}$, $V_{GS} = 0\text{ V}$ | - | | 1.5 | V | |
| t_{rr} | Reverse recovery time | $I_{SD} = 24\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times) | - | 375 | | ns | |
| Q_{rr} | Reverse recovery charge | | | 6 | | | μC |
| I_{RRM} | Reverse recovery current | | | 33 | | | |
| t_{rr} | Reverse recovery time | $I_{SD} = 24\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 60\text{ V}$, $T_j = 150\text{ °C}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times) | - | 440 | | ns | |
| Q_{rr} | Reverse recovery charge | | | 8 | | | μC |
| I_{RRM} | Reverse recovery current | | | 36 | | | |

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs, duty cycle 1.5%.

2.1 Electrical characteristics curves

Figure 1. Safe operating area

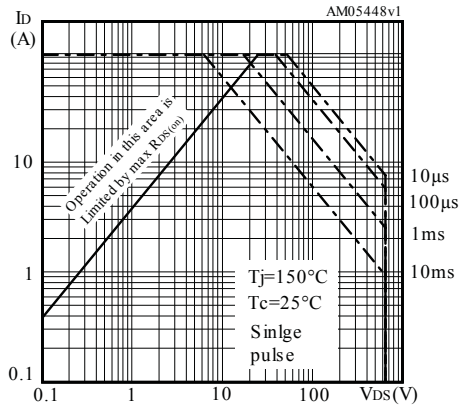


Figure 2. Thermal impedance

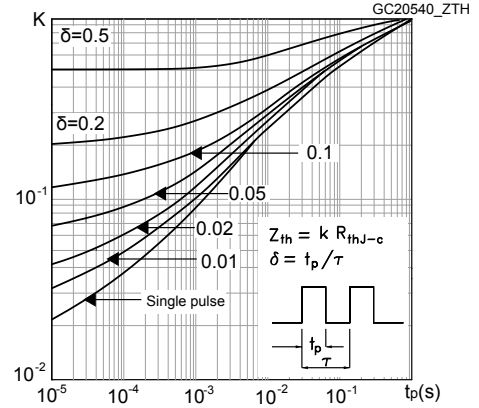


Figure 3. Output characteristics

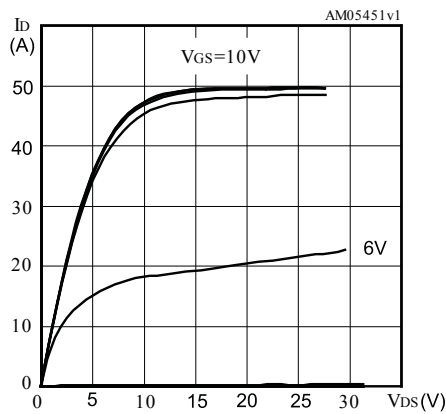


Figure 4. Transfer characteristics

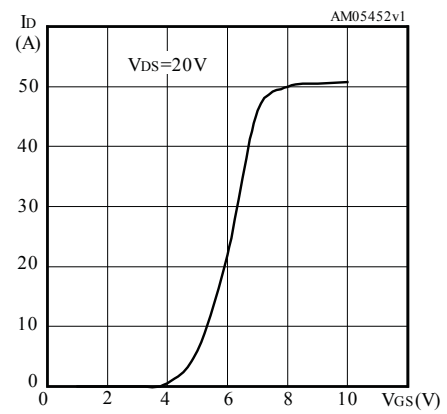


Figure 5. Gate charge vs gate-source voltage

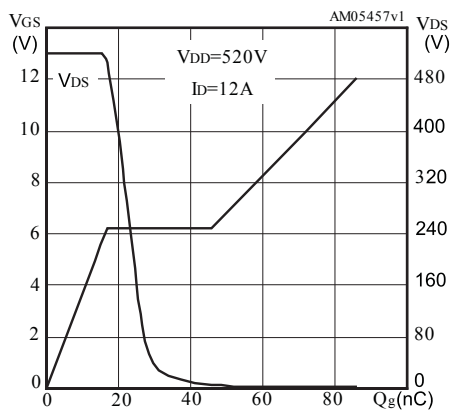


Figure 6. Static drain-source on resistance

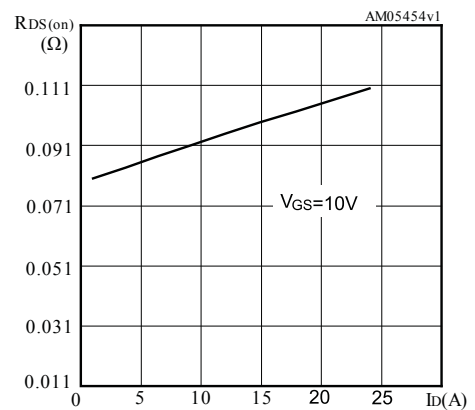


Figure 7. Capacitance variations

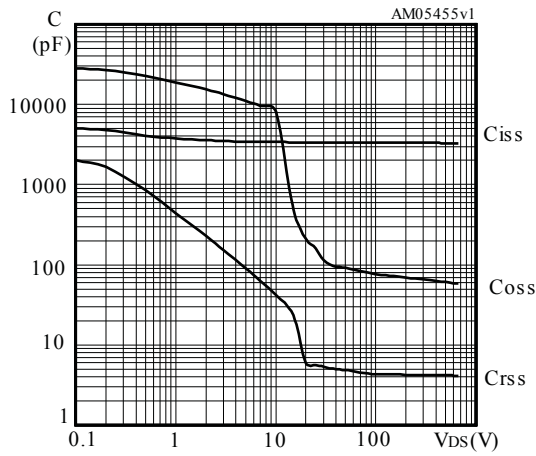


Figure 8. Output capacitance stored energy

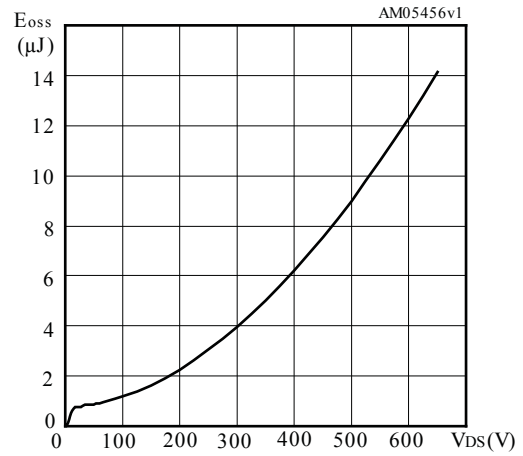


Figure 9. Normalized gate threshold voltage vs temperature

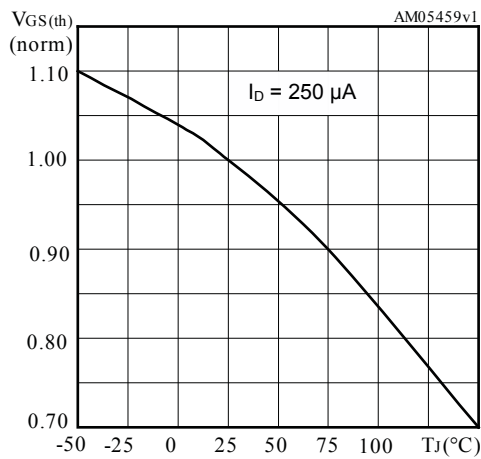


Figure 10. Normalized on resistance vs temperature



Figure 11. Source-drain diode forward characteristics

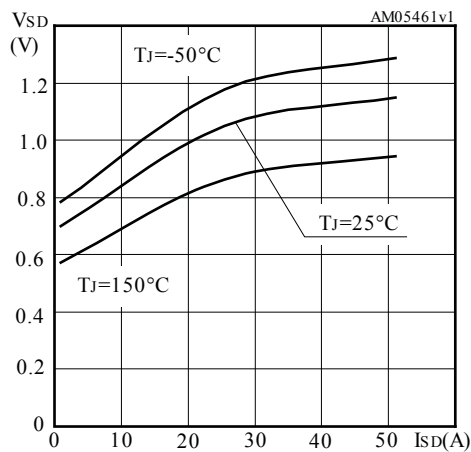


Figure 12. Normalized V_{(BR)DSS} vs temperature

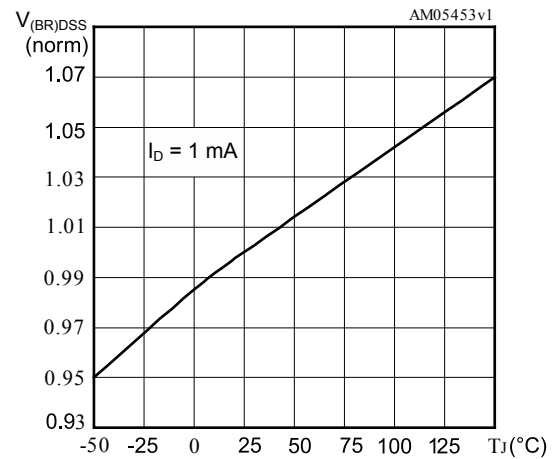
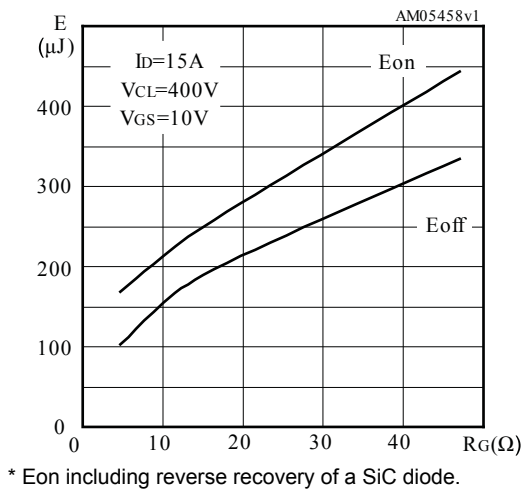


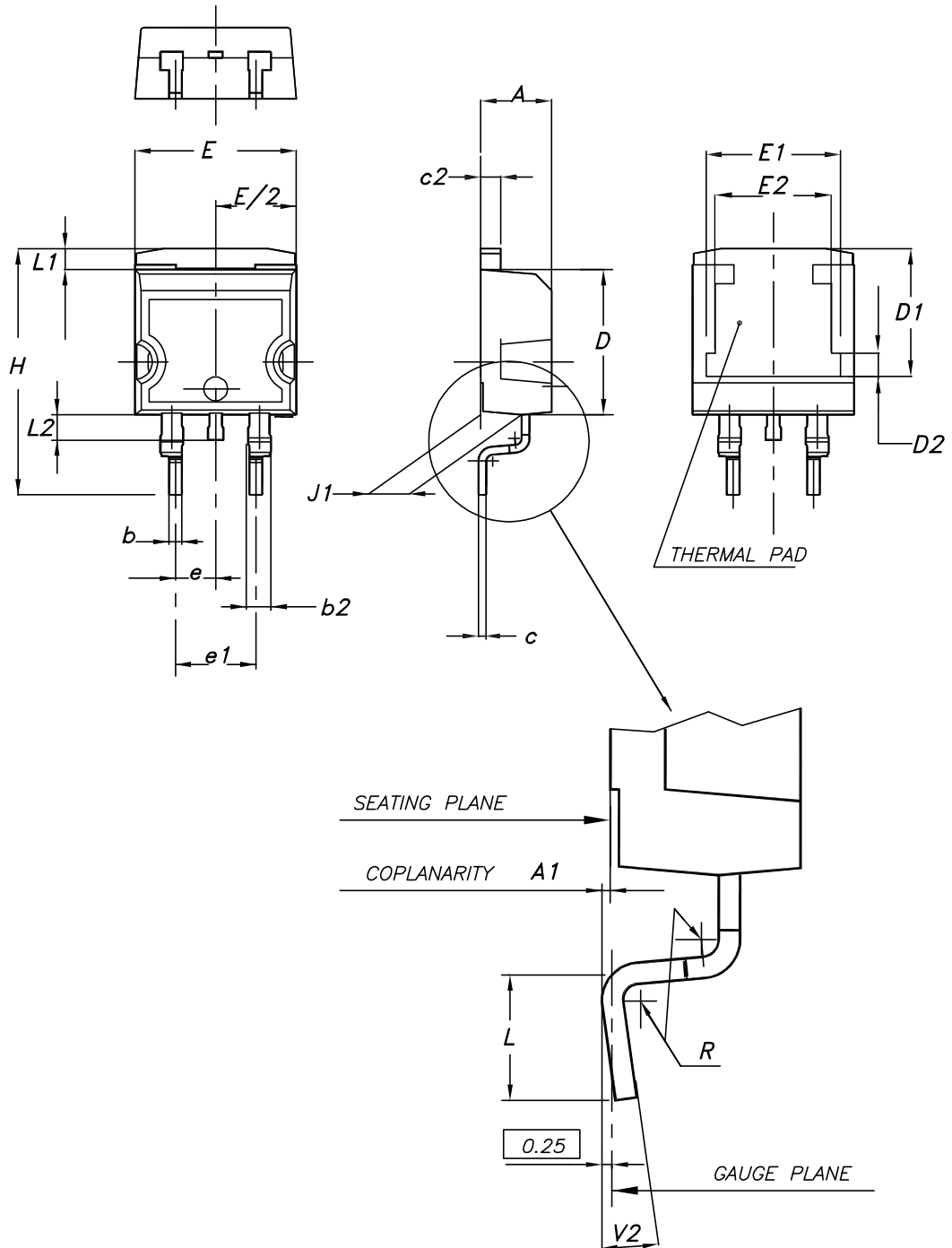
Figure 13. Switching energy vs gate resistance



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK®** packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 D²PAK (TO-263) type A package information

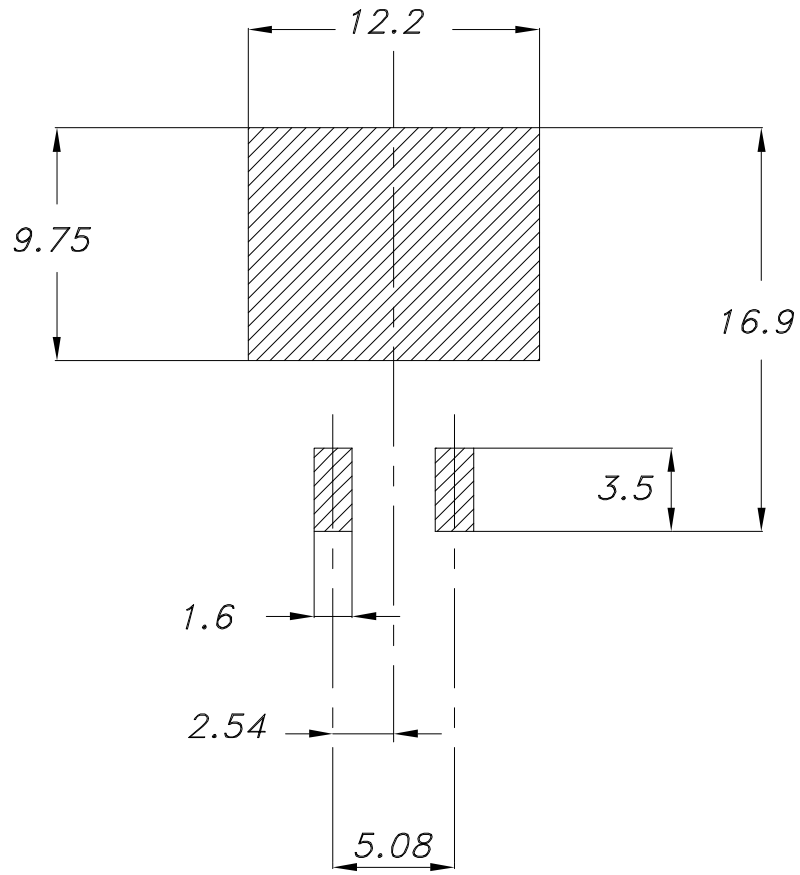
 Figure 20. D²PAK (TO-263) type A package outline


0079457_25

Table 8. D²PAK (TO-263) type A package mechanical data

| Dim. | mm | | |
|------|-------|------|-------|
| | Min. | Typ. | Max. |
| A | 4.40 | | 4.60 |
| A1 | 0.03 | | 0.23 |
| b | 0.70 | | 0.93 |
| b2 | 1.14 | | 1.70 |
| c | 0.45 | | 0.60 |
| c2 | 1.23 | | 1.36 |
| D | 8.95 | | 9.35 |
| D1 | 7.50 | 7.75 | 8.00 |
| D2 | 1.10 | 1.30 | 1.50 |
| E | 10.00 | | 10.40 |
| E1 | 8.30 | 8.50 | 8.70 |
| E2 | 6.85 | 7.05 | 7.25 |
| e | | 2.54 | |
| e1 | 4.88 | | 5.28 |
| H | 15.00 | | 15.85 |
| J1 | 2.49 | | 2.69 |
| L | 2.29 | | 2.79 |
| L1 | 1.27 | | 1.40 |
| L2 | 1.30 | | 1.75 |
| R | | 0.40 | |
| V2 | 0° | | 8° |

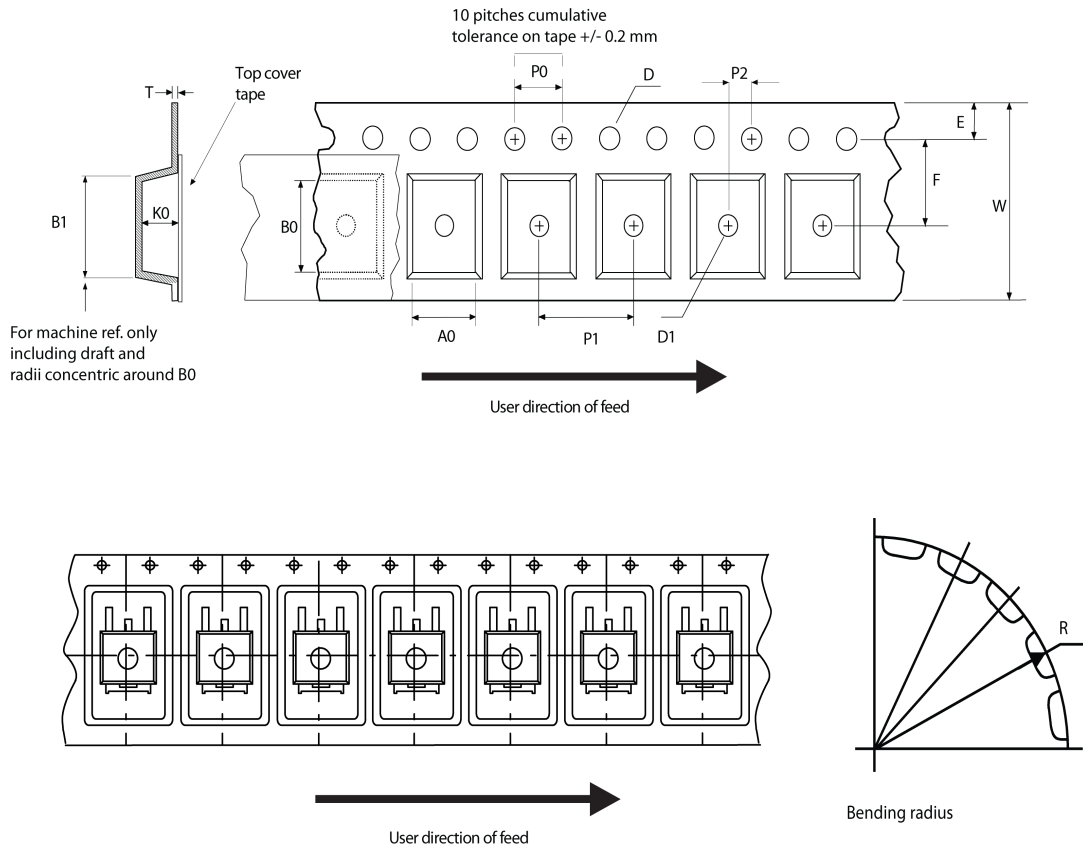
Figure 21. D²PAK (TO-263) recommended footprint (dimensions are in mm)



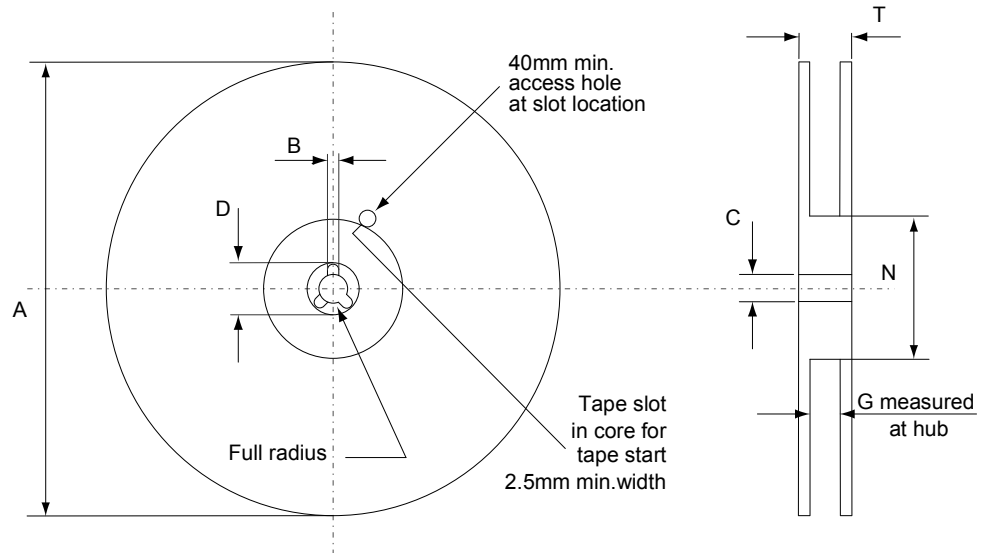
Footprint

4.2 D²PAK packing information

Figure 22. D²PAK tape outline



AM08852v1

Figure 23. D²PAK reel outline


AM06038v1

Table 9. D²PAK tape and reel mechanical data

| Tape | | | Reel | | | |
|------|------|------|--------------------------------|------|------|------|
| Dim. | mm | | Dim. | mm | | |
| | Min. | Max. | | Min. | Max. | |
| A0 | 10.5 | 10.7 | A | | 330 | |
| B0 | 15.7 | 15.9 | B | 1.5 | | |
| D | 1.5 | 1.6 | C | 12.8 | 13.2 | |
| D1 | 1.59 | 1.61 | D | 20.2 | | |
| E | 1.65 | 1.85 | G | 24.4 | 26.4 | |
| F | 11.4 | 11.6 | N | 100 | | |
| K0 | 4.8 | 5.0 | T | | 30.4 | |
| P0 | 3.9 | 4.1 | Base quantity Bulk quantity | | | |
| P1 | 11.9 | 12.1 | | | | 1000 |
| P2 | 1.9 | 2.1 | | | | 1000 |
| R | 50 | | | | | |
| T | 0.25 | 0.35 | | | | |
| W | 23.7 | 24.3 | | | | |

Revision history

Table 10. Document revision history

| Date | Version | Changes |
|-------------|---------|---|
| 16-Jan-2009 | 1 | First release |
| 01-Sep-2009 | 2 | Document status promoted from preliminary data to datasheet. |
| 30-Sep-2009 | 3 | Corrected V_{GS} value on Table 2: Absolute maximum ratings |
| 06-Oct-2011 | 4 | <p>$C_{o(er)}$ and $C_{o(tr)}$ values changed in <i>Table 5: Dynamic</i></p> <p><i>Table 6: Switching times</i> parameters updates</p> <p><i>Figure 24: Switching time waveform</i> has been corrected</p> <p>Minor text changes</p> <p><i>Section 4: Package mechanical data</i> has been modified. Added:</p> <ul style="list-style-type: none"> – <i>Table 8: D²PAK (TO-263) mechanical data, Figure 25: D²PAK (TO-263) drawing and Figure 26: D²PAK footprint,</i> – <i>Table 9: TO-220FP mechanical data, and Figure 27: TO-220FP drawing;</i> – <i>Table 10: I²PAK (TO-262) mechanical data, and Figure 28: I²PAK (TO-262) drawing;</i> – <i>Table 11: TO-220 type A mechanical data, and Figure 29: TO-220 type A drawing;</i> – <i>Table 12: TO-247 mechanical data, and Figure 30: TO-247 drawing;</i> <p><i>Section 5: Packaging mechanical data</i> has been modified. Added:</p> <ul style="list-style-type: none"> – <i>Table 13: D²PAK (TO-263) tape and reel mechanical data, Figure 31: Tape and Figure 32: Reel;</i> |
| 02-Nov-2018 | 5 | <p>The part numbers STF32N65M5, STI32N65M5, STP32N65M5, STW32N65M5 have been moved to a separate datasheet.</p> <p>Content reworked to improve readability, no technical changes.</p> |

Contents

| | | |
|------------|--|-----------|
| 1 | Electrical ratings | 2 |
| 2 | Electrical characteristics | 3 |
| 2.1 | Electrical characteristics curves | 5 |
| 3 | Test circuits | 8 |
| 4 | Package information | 9 |
| 4.1 | D ² PAK (TO-263) type A package information | 9 |
| 4.2 | D ² PAK packing information | 12 |
| | Revision history | 15 |

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved